



PROCESS - HIGHLIGHTS

- Requires less floor-space than conventional lamination
- Lower equipment investment
- Significantly reduced energy consumption
- Faster cycle times as no lamination is required
- Outstanding UV stability
- Higher module efficiency due to better light transmission
- No discoloration
- High temperature and electrical stability
- Saving of operators
- Applicable for cell-modules, thin film modules and glass-glass modules

REIS ROBOTICS

FULLY AUTOMATED LIQUID ENCAPSULATION FOR MODULES IN PHOTOVOLTAICS

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